



Material Content Data Sheet



Sales Product Name		SPD18P06P G		Issued		20. July 2018		
MA#		MA000446578						
Package		PG-TO252-3-311		Weight*		315.07 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.472	0.78	0.78	7845	7845
leadframe	non noble metal	iron	7439-89-6	0.143	0.05		455	
	inorganic material	phosphorus	7723-14-0	0.043	0.01		136	
	non noble metal	copper	7440-50-8	143.098	45.42	45.48	454175	454766
wire	non noble metal	aluminium	7429-90-5	10.462	3.32	3.32	33205	33205
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.870	0.59		5935	
	plastics	brominated resin	-	2.004	0.64		6359	
	organic material	carbon black	1333-86-4	2.137	0.68		6783	
	plastics	epoxy resin	-	18.033	5.72		57234	
	inorganic material	silicondioxide	60676-86-0	109.534	34.76	42.39	347647	423958
leadfinish	non noble metal	tin	7440-31-5	3.787	1.20	1.20	12019	12019
plating	non noble metal	nickel	7440-02-0	0.086	0.03		274	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.03	1	275
solder	noble metal	silver	7440-22-4	0.055	0.02		175	
	non noble metal	tin	7440-31-5	0.044	0.01		140	
	non noble metal	lead	7439-92-1	2.102	0.67	0.70	6671	6986
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		61	
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	copper	7440-50-8	19.177	6.09	6.10	60867	60946
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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